

256K (32K x 8) CMOS EPROM

FEATURES

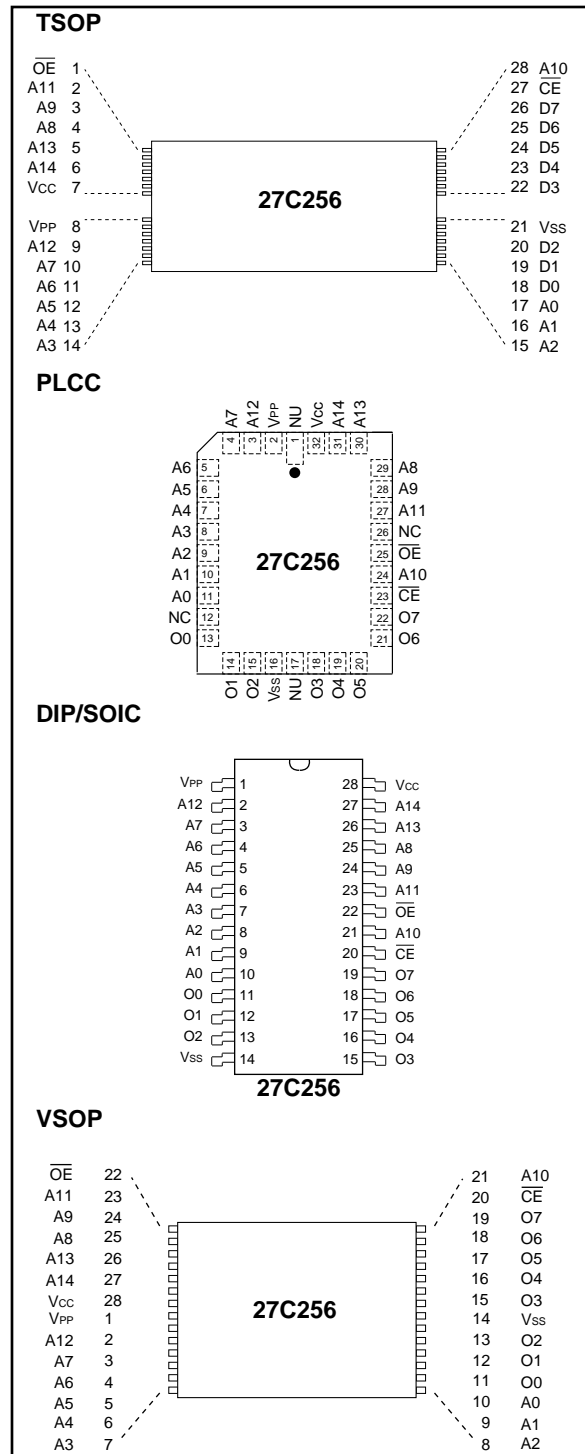
- High speed performance
 - 90 ns access time available
- CMOS Technology for low power consumption
 - 20 mA Active current
 - 100 μ A Standby current
- Factory programming available
- Auto-insertion-compatible plastic packages
- Auto ID aids automated programming
- Separate chip enable and output enable controls
- High speed "express" programming algorithm
- Organized 32K x 8: JEDEC standard pinouts
 - 28-pin Dual-in-line package
 - 32-pin PLCC Package
 - 28-pin SOIC package
 - 28-pin Thin Small Outline Package (TSOP)
 - 28-pin Very Small Outline Package (VSOP)
 - Tape and reel
- Data Retention > 200 years
- Available for the following temperature ranges:
 - Commercial: 0°C to +70°C
 - Industrial: -40°C to +85°C
 - Automotive: -40°C to +125°C

DESCRIPTION

The Microchip Technology Inc. 27C256 is a CMOS 256K bit electrically Programmable Read Only Memory (EPROM). The device is organized as 32K words by 8 bits (32K bytes). Accessing individual bytes from an address transition or from power-up (chip enable pin going low) is accomplished in less than 90 ns. This very high speed device allows the most sophisticated micro-processors to run at full speed without the need for WAIT states. CMOS design and processing enables this part to be used in systems where reduced power consumption and reliability are requirements.

A complete family of packages is offered to provide the most flexibility in applications. For surface mount applications, PLCC, SOIC, VSOP or TSOP packaging is available. Tape and reel packaging is also available for PLCC or SOIC packages.

PACKAGE TYPE



1.0 ELECTRICAL CHARACTERISTICS

1.1 Maximum Ratings*

VCC and input voltages w.r.t. VSS..... -0.6V to +7.25V
 VPP voltage w.r.t. VSS during programming -0.6V to +14.0V
 Voltage on A9 w.r.t. VSS -0.6V to +13.5V
 Output voltage w.r.t. VSS -0.6V to VCC +1.0V
 Storage temperature -65°C to +150°C
 Ambient temp. with power applied -65°C to +125°C

*Notice: Stresses above those listed under "Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

TABLE 1-1: PIN FUNCTION TABLE

Name	Function
A0-A14	Address Inputs
\overline{CE}	Chip Enable
\overline{OE}	Output Enable
VPP	Programming Voltage
O0 - O7	Data Output
VCC	+5V Power Supply
VSS	Ground
NC	No Connection; No Internal Connection
NU	Not Used; No External Connection Is Allowed

TABLE 1-2: READ OPERATION DC CHARACTERISTICS

VCC = +5V (±10%) Commercial: Tamb = 0°C to +70°C Industrial: Tamb = -40°C to +85°C Extended (Automotive): Tamb = -40°C to +125°C							
Parameter	Part*	Status	Symbol	Min.	Max.	Units	Conditions
Input Voltages	all	Logic "1" Logic "0"	V _{IH} V _{IL}	2.0 -0.5	V _{CC} +1 0.8	V V	
Input Leakage	all	—	I _{LI}	-10	10	µA	V _{IN} = 0 to V _{CC}
Output Voltages	all	Logic "1" Logic "0"	V _{OH} V _{OL}	2.4	0.45	V V	I _{OH} = -400 µA I _{OL} = 2.1 mA
Output Leakage	all	—	I _{LO}	-10	10	µA	V _{OUT} = 0V to V _{CC}
Input Capacitance	all	—	C _{IN}	—	6	pF	V _{IN} = 0V; Tamb = 25°C; f = 1 MHz
Output Capacitance	all	—	C _{OUT}	—	12	pF	V _{OUT} = 0V; Tamb = 25°C; f = 1 MHz
Power Supply Current, Active	C I,E	TTL input TTL input	I _{CC1} I _{CC2}	—	20 25	mA mA	V _{CC} = 5.5V; V _{PP} = V _{CC} f = 1 MHz; $\overline{OE} = \overline{CE} = V_{IL}$; I _{OUT} = 0 mA; V _{IL} = -0.1 to 0.8V; V _{IH} = 2.0 to V _{CC} ; Note 1
Power Supply Current, Standby	C I, E all	TTL input TTL input CMOS input	I _{CC(S)}	—	2 3 100	mA mA µA	$\overline{CE} = V_{CC} \pm 0.2V$
IPP Read Current VPP Read Voltage	all all	Read Mode Read Mode	I _{PP} V _{PP}	V _{CC} -0.7	100 V _{CC}	µA V	V _{PP} = 5.5V Note 2

* Parts: C=Commercial Temperature Range; I, E=Industrial and Extended Temperature Ranges

Note 1: Typical active current increases .75 mA per MHz up to operating frequency for all temperature ranges.

Note 2: V_{CC} must be applied before V_{PP}, and be removed simultaneously or after V_{PP}.

TABLE 1-3: READ OPERATION AC CHARACTERISTICS

		AC Testing Waveform: $V_{IH} = 2.4V$ and $V_{IL} = 0.45V$; $V_{OH} = 2.0V$ $V_{OL} = 0.8V$ Output Load: 1 TTL Load + 100 pF Input Rise and Fall Times: 10 ns Ambient Temperature: Commercial: $T_{amb} = 0^{\circ}C$ to $+70^{\circ}C$ Industrial: $T_{amb} = -40^{\circ}C$ to $+85^{\circ}C$ Automotive: $T_{amb} = -40^{\circ}C$ to $+125^{\circ}C$											
Parameter	Sym	27C256-90*		27C256-10*		27C256-12		27C256-15		27C256-20		Units	Conditions
		Min	Max	Min	Max	Min	Max	Min	Max	Min	Max		
Address to Output Delay	tACC	—	90	—	100	—	120	—	150	—	200	ns	$\overline{CE} = \overline{OE} = V_{IL}$
\overline{CE} to Output Delay	tCE	—	90	—	100	—	120	—	150	—	200	ns	$\overline{OE} = V_{IL}$
\overline{OE} to Output Delay	tOE	—	40	—	45	—	55	—	65	—	75	ns	$\overline{CE} = V_{IL}$
\overline{CE} or \overline{OE} to O/P High Impedance	tOFF	0	30	0	30	0	35	0	50	0	55	ns	
Output Hold from Address \overline{CE} or \overline{OE} , whichever goes first	tOH	0	—	0	—	0	—	0	—	0	—	ns	

* -10, -90 AC Testing Waveform: $V_{IH} = 2.4V$ and $V_{IL} = .45V$; $V_{OH} = 1.5V$ and $V_{OL} = 1.5V$
Output Load: 1 TTL Load + 30pF

FIGURE 1-1: READ WAVEFORMS

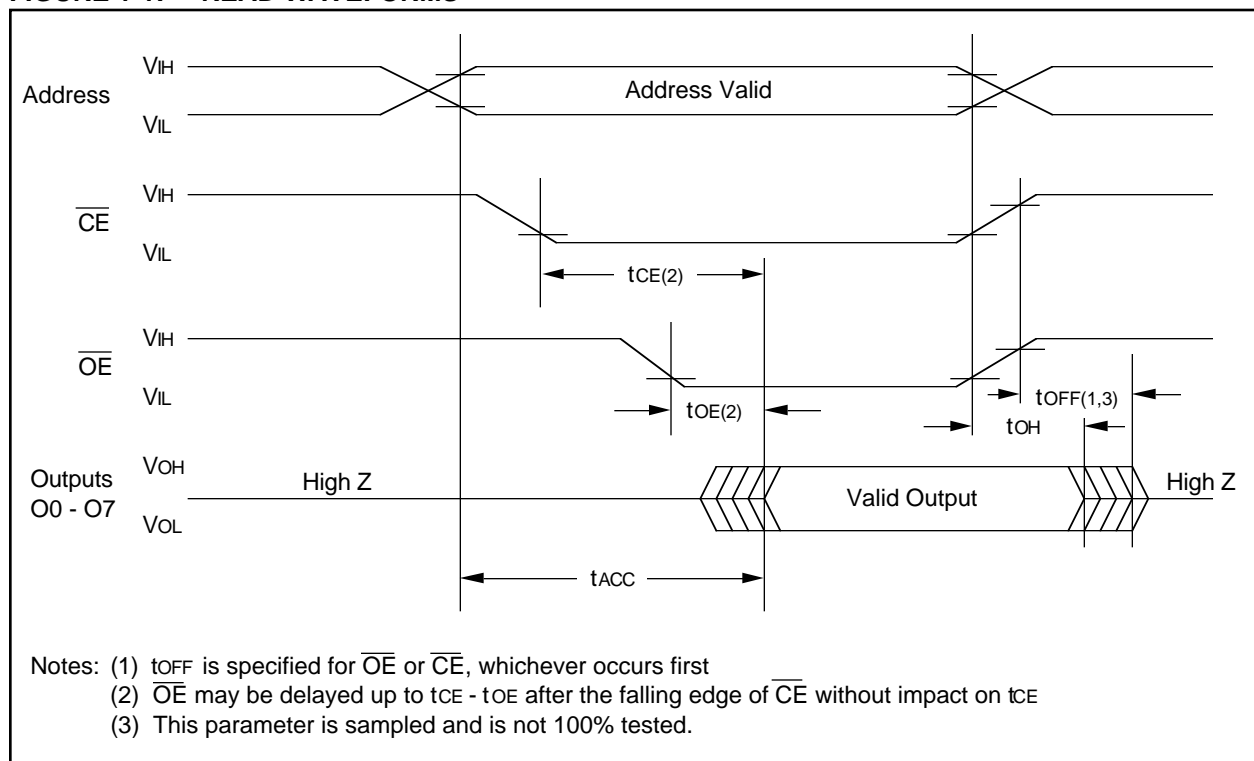


TABLE 1-4: PROGRAMMING DC CHARACTERISTICS

Ambient Temperature: $T_{amb} = 25^{\circ}\text{C} \pm 5^{\circ}\text{C}$ $V_{CC} = 6.5\text{V} \pm 0.25\text{V}$, $V_{PP} = V_H = 13.0\text{V} \pm 0.25\text{V}$						
Parameter	Status	Symbol	Min	Max.	Units	Conditions
Input Voltages	Logic"1"	V_{IH}	2.0	$V_{CC}+1$	V	
	Logic"0"	V_{IL}	-0.1	0.8	V	
Input Leakage	—	I_{LI}	-10	10	μA	$V_{IN} = 0\text{V to } V_{CC}$
Output Voltages	Logic"1"	V_{OH}	2.4		V	$I_{OH} = -400\ \mu\text{A}$
	Logic"0"	V_{OL}		0.45	V	$I_{OL} = 2.1\ \text{mA}$
VCC Current, program & verify	—	I_{CC2}	—	20	mA	Note 1
VPP Current, program	—	I_{PP2}	—	25	mA	Note 1
A9 Product Identification	—	V_H	11.5	12.5	V	

Note 1: VCC must be applied simultaneously or before VPP and removed simultaneously or after VPP

TABLE 1-5: PROGRAMMING AC CHARACTERISTICS

for Program, Program Verify and Program Inhibit Modes						
AC Testing Waveform: $V_{IH}=2.4\text{V}$ and $V_{IL}=0.45\text{V}$; $V_{OH}=2.0\text{V}$; $V_{OL}=0.8\text{V}$ Output Load: 1 TTL Load + 100pF Ambient Temperature: $T_{amb}=25^{\circ}\text{C} \pm 5^{\circ}\text{C}$ $V_{CC}= 6.5\text{V} \pm 0.25\text{V}$, $V_{PP} = V_H = 13.0\text{V} \pm 0.25\text{V}$						
Parameter	Symbol	Min.	Max.	Units	Remarks	
Address Set-Up Time	tAS	2	—	μs		
Data Set-Up Time	tDS	2	—	μs		
Data Hold Time	tDH	2	—	μs		
Address Hold Time	tAH	0	—	μs		
Float Delay (2)	tDF	0	130	ns		
VCC Set-Up Time	tVCS	2	—	μs		
Program Pulse Width (1)	tPW	95	105	μs	100 μs typical	
$\overline{\text{CE}}$ Set-Up Time	tCES	2	—	μs		
$\overline{\text{OE}}$ Set-Up Time	tOES	2	—	μs		
VPP Set-Up Time	tVPS	2	—	μs		
Data Valid from $\overline{\text{OE}}$	tOE	—	100	ns		

Note 1: For express algorithm, initial programming width tolerance is $100\ \mu\text{s} \pm 5\%$.

Note 2: This parameter is only sampled and not 100% tested. Output float is defined as the point where data is no longer driven (see timing diagram).

FIGURE 1-2: PROGRAMMING WAVEFORMS

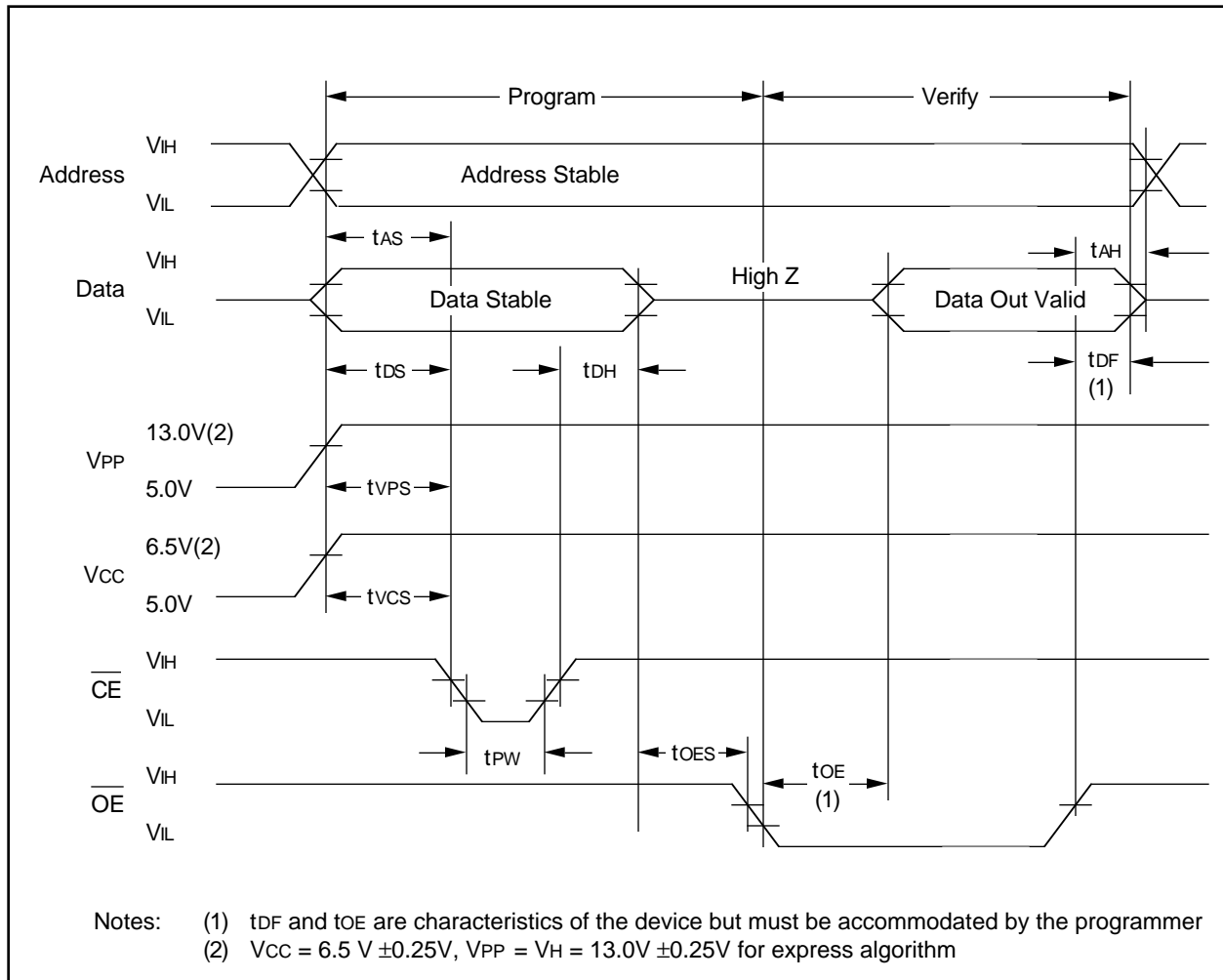


TABLE 1-6: MODES

Operation Mode	\overline{CE}	OE	VPP	A9	O0 - O7
Read	VIL	VIL	VCC	X	DOUT
Program	VIL	VIH	VH	X	DIN
Program Verify	VIH	VIL	VH	X	DOUT
Program Inhibit	VIH	VIH	VH	X	High Z
Standby	VIH	X	VCC	X	High Z
Output Disable	VIL	VIH	VCC	X	High Z
Identity	VIL	VIL	VCC	VH	Identity Code

X = Don't Care

1.2 Read Mode

(See Timing Diagrams and AC Characteristics)

Read Mode is accessed when:

- the \overline{CE} pin is low to power up (enable) the chip
- the \overline{OE} pin is low to gate the data to the output pins

For Read operations, if the addresses are stable, the address access time (t_{ACC}) is equal to the delay from \overline{CE} to output (t_{CE}). Data is transferred to the output after a delay from the falling edge of \overline{OE} (t_{OE}).

1.3 Standby Mode

The standby mode is defined when the \overline{CE} pin is high (VIH) and a program mode is not defined.

When these conditions are met, the supply current will drop from 20 mA to 100 μ A.

1.4 Output Enable

This feature eliminates bus contention in multiple bus microprocessor systems and the outputs go to a high impedance when the following condition is true:

- The \overline{OE} pin is high and the program mode is not defined.

1.5 Erase Mode (U.V. Windowed Versions)

Windowed products offer the ability to erase the memory array. The memory matrix is erased to the all 1's state when exposed to ultraviolet light. To ensure complete erasure, a dose of 15 watt-second/cm² is required. This means that the device window must be placed within one inch and directly underneath an ultraviolet lamp with a wavelength of 2537 Angstroms, intensity of 12,000 μ W/cm² for approximately 20 minutes.

1.6 Programming Mode

The Express Algorithm has been developed to improve on the programming throughput times in a production environment. Up to ten 100-microsecond pulses are applied until the byte is verified. No overprogramming is required. A flowchart of the express algorithm is shown in Figure 1-3.

Programming takes place when:

- VCC is brought to the proper voltage,
- VPP is brought to the proper VH level,
- the \overline{OE} pin is high, and
- the \overline{CE} pin is low.

Since the erased state is "1" in the array, programming of "0" is required. The address to be programmed is set via pins A0-A14 and the data to be programmed is presented to pins O0-O7. When data and address are stable, a low going pulse on the \overline{CE} line programs that location.

1.7 Verify

After the array has been programmed it must be verified to ensure all the bits have been correctly programmed. This mode is entered when all the following conditions are met:

- VCC is at the proper level,
- VPP is at the proper VH level,
- the \overline{CE} line is high, and
- the \overline{OE} line is low.

1.8 Inhibit

When programming multiple devices in parallel with different data, only \overline{CE} need be under separate control to each device. By pulsing the \overline{CE} line low on a particular device, that device will be programmed; all other devices with \overline{CE} held high will not be programmed with the data, although address and data will be available on their input pins.

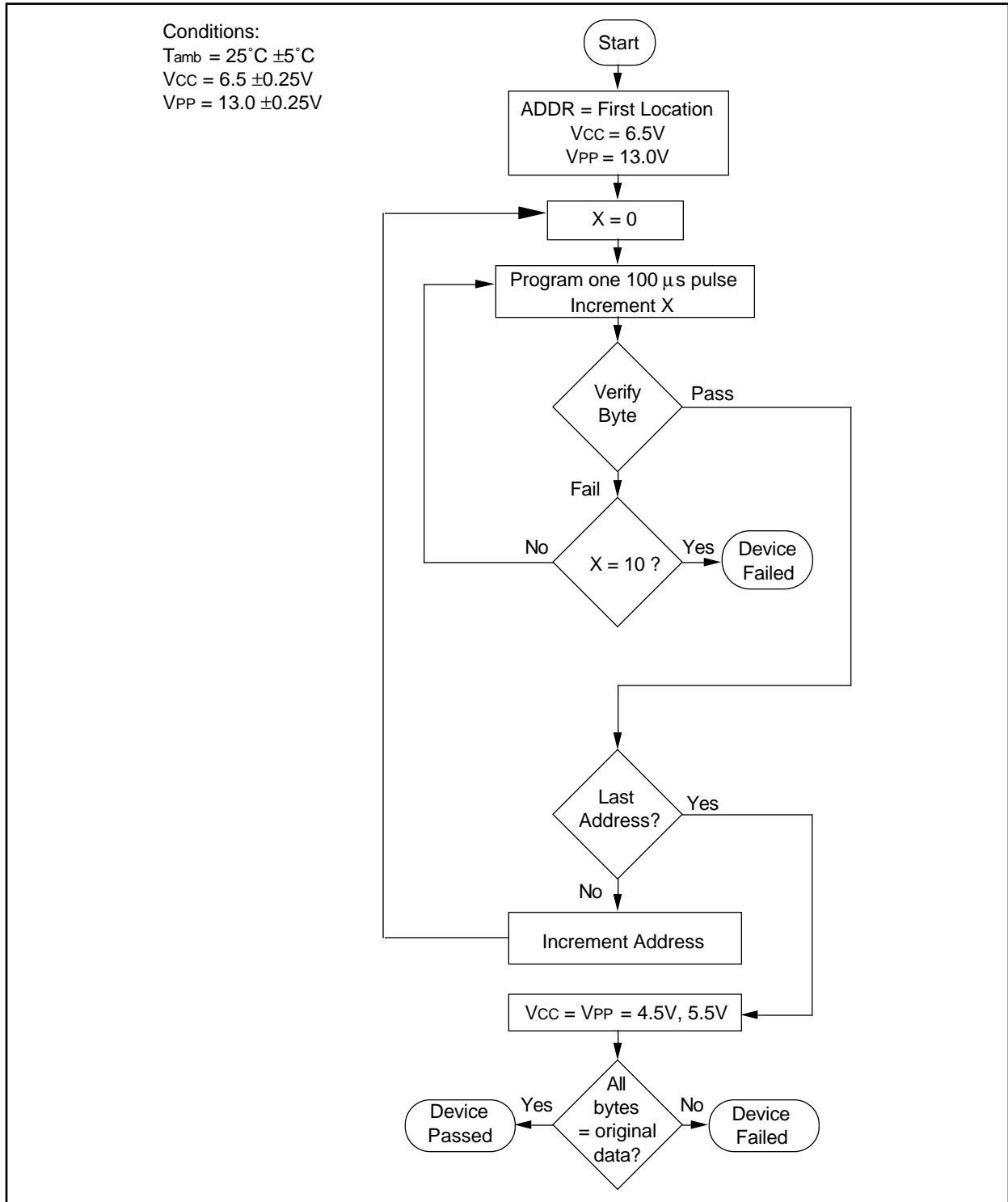
1.9 Identity Mode

In this mode specific data is output which identifies the manufacturer as Microchip Technology Inc. and device type. This mode is entered when Pin A9 is taken to VH (11.5V to 12.5V). The \overline{CE} and \overline{OE} lines must be at VIL. A0 is used to access any of the two non-erasable bytes whose data appears on O0 through O7.

Pin \rightarrow	Input	Output								
Identity \downarrow	A0	0 7	0 6	0 5	0 4	0 3	0 2	0 1	0 0	H e x
Manufacturer	VIL	0	0	1	0	1	0	0	1	29
Device Type*	VIH	1	0	0	0	1	1	0	0	8C

* Code subject to change

FIGURE 1-3: PROGRAMMING EXPRESS ALGORITHM



27C256

27C256 Product Identification System

To order or to obtain information (e.g., on pricing or delivery), please use listed part numbers, and refer to factory or listed sales offices.

27C256 - 90 I /TS			
Package:	L	Plastic Leaded Chip Carrier	
	P	Plastic DIP	
	SO	Plastic SOIC	
	TS	Thin Small Outline Package (TSOP) 8x20mm	
	VS	Very Small Outline Package (VSOP) 8x13.4mm	
Temperature Range:	-	0°C to +70°C	
	I	-40°C to +85°C	
	E	-40°C to +125°C	
Access Time:	90	90 ns	
	10	100 ns	
	12	120 ns	
	15	150 ns	
	20	200 ns	
Device	27C256	256K (32K x 8) CMOS EPROM	

AMERICAS

Corporate Office

Microchip Technology Inc.
2355 West Chandler Blvd.
Chandler, AZ 85224-6199
Tel: 602 786-7200 Fax: 602 786-7277
Technical Support: 602 786-7627
Web: <http://www.mchip.com/biz/mchip>

Atlanta

Microchip Technology Inc.
500 Sugar Mill Road, Suite 200B
Atlanta, GA 30350
Tel: 770 640-0034 Fax: 770 640-0307

Boston

Microchip Technology Inc.
5 Mount Royal Avenue
Marlborough, MA 01752
Tel: 508 480-9990 Fax: 508 480-8575

Chicago

Microchip Technology Inc.
333 Pierce Road, Suite 180
Itasca, IL 60143
Tel: 708 285-0071 Fax: 708 285-0075

Dallas

Microchip Technology Inc.
14651 Dallas Parkway, Suite 816
Dallas, TX 75240-8809
Tel: 214 991-7177 Fax: 214 991-8588

Dayton

Microchip Technology Inc.
35 Rockridge Road
Englewood, OH 45322
Tel: 513 832-2543 Fax: 513 832-2841

Los Angeles

Microchip Technology Inc.
18201 Von Karman, Suite 455
Irvine, CA 92715
Tel: 714 263-1888 Fax: 714 263-1338

New York

Microchip Technology Inc.
150 Motor Parkway, Suite 416
Hauppauge, NY 11788
Tel: 516 273-5305 Fax: 516 273-5335

AMERICAS (continued)

San Jose

Microchip Technology Inc.
2107 North First Street, Suite 590
San Jose, CA 95131
Tel: 408 436-7950 Fax: 408 436-7955

ASIA/PACIFIC

Hong Kong

Microchip Technology
Unit No. 3002-3004, Tower 1
Metroplaza
223 Hing Fong Road
Kwai Fong, N.T. Hong Kong
Tel: 852 2 401 1200 Fax: 852 2 401 3431

Korea

Microchip Technology
168-1, Youngbo Bldg. 3 Floor
Samsung-Dong, Kangnam-Ku,
Seoul, Korea
Tel: 82 2 554 7200 Fax: 82 2 558 5934

Singapore

Microchip Technology
200 Middle Road
#10-03 Prime Centre
Singapore 188980
Tel: 65 334 8870 Fax: 65 334 8850

Taiwan

Microchip Technology
10F-1C 207
Tung Hua North Road
Taipei, Taiwan, ROC
Tel: 886 2 717 7175 Fax: 886 2 545 0139

EUROPE

United Kingdom

Arizona Microchip Technology Ltd.
Unit 6, The Courtyard
Meadow Bank, Furlong Road
Bourne End, Buckinghamshire SL8 5AJ
Tel: 44 0 1628 851077 Fax: 44 0 1628 850259

France

Arizona Microchip Technology SARL
2 Rue du Buisson aux Fraises
91300 Massy - France
Tel: 33 1 69 53 63 20 Fax: 33 1 69 30 90 79

Germany

Arizona Microchip Technology GmbH
Gustav-Heinemann-Ring 125
D-81739 Muenchen, Germany
Tel: 49 89 627 144 0 Fax: 49 89 627 144 44

Italy

Arizona Microchip Technology SRL
Centro Direzionale Colleoni
Palazzo Pegaso Ingresso No. 2
Via Paracelso 23, 20041
Agrate Brianza (MI) Italy
Tel: 39 039 689 9939 Fax: 39 039 689 9883

JAPAN

Microchip Technology Intl. Inc.
Benex S-1 6F
3-18-20, Shin Yokohama
Kohoku-Ku, Yokohama
Kanagawa 222 Japan
Tel: 81 45 471 6166 Fax: 81 45 471 6122

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